Replace the paragraph beginning at page 3, line 7 with:

Furthermore, the conventional semiconductor package requires a region coated with the adhesive 2 on the upper surface of the semiconductor chip 1 in order to adhere the LOC type leads 3, and the electrode pads 7 cannot be provided in the region coated with the adhesive 2. For this reason, the area on the chip 1 for arranging the electrode pads 7 is restricted to the central region (for the central electrode pads 7a) and the peripheral regions (for the peripheral electrode pads 7b) along shorter sides where the standard type leads 6 are provided. Thus, there has been a drawback in that the region on the upper surface of the semiconductor chip where the electrode pads 7 are to be provided is limited to a small I-shaped region.

Replace the paragraph beginning at page 3, line 27 with:

In the conventional semiconductor package shown in Fig. 16, the S bend of LOC type lead 3 must be located at a region in which the leads 3 are arranged rectilinearly, in parallel, in the vicinity of the outer leads 3b extending from the sealing resin. If the S bend of the LOC type lead 3 is located at a region in which the leads 3 are arranged obliquely, spacing between tips of the adjacent LOC type inner leads 3a easily becomes uneven so that the tips of the adjacent leads come in contact with each other or necessary space cannot be obtained. In the conventional semiconductor package shown in Fig. 16, leads 6 on four corners have no bent portion and other leads 3 are bent so that the leads 6 and the leads 3 are not in the same plane. Accordingly, there have been drawbacks in that a high working cost for bending is required and leads must be handled carefully so as not to be deformed.

IN THE CLAIMS:

Replace the indicated claims with:

1. (Amended) A semiconductor package comprising a semiconductor chip, a die pad, a die bond material fixing the semiconductor chip to the die pad, lead-on-chip (LOC) inner leads having tips spaced from and extending across the semiconductor chip, and metal wires connecting the tips of the LOC inner leads to electrode pads on the